Photomicrosensor (Transmissive) EE-SX3340/EE-SX4340

Compact Slot / SMD Type (Slot width: 4 mm)

- Unique 4 mm Slot width.
- PCB surface mounting type.
- High resolution with a 0.5-mm-wide aperture.
- Choice of 2 types of Photo-IC output (EE-SX3340: Dark ON, EE-SX4340: Light ON).

Be sure to read Safety Precautions on page 3.

Ordering Information

Photomicrosensor

Appearance	Sensing method	Connecting method	Sensing distance	Aperture size (H $ imes$ W) (mm)	Output type	Model				
5.5	Transmissive (slot type)	SMT	4 mm (Slot width)	Emitter 1.04 × 1.4 Detector 1.4 × 0.5	Photo IC	EE-SX3340 (Dark-ON) EE-SX4340 (Light-ON)				

Ratings, Characteristics and Exterior Specifications

Item Symbol Rated value Unit Remarks Emitter Forward current 30 mΑ ---- *1 IF Reverse voltage VR 4 V ---Detector Power supply Vcc 16 V --voltage V Output voltage Vout 28 ____ **Output current** Ιουτ 16 mΑ ---Permissible Pout 80 mW ---- *1 output dissipation Operating °C -30 to +85 Topr ---- *1 temperature Storage -40 to +100 °C Tstg ---- *1 temperature **Reflow soldering** 10 sec. Tsol 255 °C temperature max. *2

Absolute Maximum Ratings (Ta = 25°C)

*1. Continuous Forward Current and Collector Power Dissipation must be derated complying. The product should be used without freezing or condensation.

***2.** In case of reflow soldering, conditions which are shown at the temperature profile should be kept.

Exterior Specifications

Connecting method	Weight (g)	Material		
Connecting method	weight (g)	Case		
SMT	0.2	PPS		

Electrical and Optical Characteristics (Ta = 25°C)

Item		Symbol	Value			Unit	Condition
		Symbol	MIN.	TYP.	MAX.	Unit	Condition
E	mitter						
	Forward voltage	VF		1.2	1.5	V	I⊧ = 20 mA
	Reverse current	Ir		0.01	10	μΑ	V _R = 4 V
	Peak emission wavelength	λP		940		nm	IF = 20 mA
C	etector						
	Power supply voltage	Vcc	4.5		16	V	
	Low-level output voltage	Vol		0.12	0.4	V	Vcc = 4.5 to 16 V IF = 0 mA (EE-SX3340) IF = 10 mA (EE-SX4340) IoL=16 mA
	High-level output voltage	Іон			100	μΑ	Vcc = 4.5 to 16 V IF = 10 mA (EE-SX3340) IF = 0 mA (EE-SX4340) Vон = 28 V
	Current consumption	Icc		4	10	mA	Vcc = 4.5 to 16 V
	Peak spectral sensitivity wavelength	λP		870		nm	Vcc = 4.5 to 16 V
LED current when output is OFF (EE-SX3340) LED current when output is ON (EE-SX4340)		IFT			8	mA	Vcc = 4.5 to 16 V
ŀ	lysteresis	$\triangle H$		15		%	Vcc = 4.5 to 16 V *1
Response frequency		f	3			kHz	Vcc = 4.5 to 16 V IF = 20 mA IoL = 16 mA *2
Response delay time		tрін (tphl)		6		μs	Vcc = 4.5 to 16 V I⊧ = 20 mA Io∟ = 16 mA *3
Response delay time		tрнг (tplн)		10		μs	Vcc = 4.5 to 16 V I⊧ = 20 mA Io∟=16 mA *3



***3.** The following illustrations show the definition of response delay

time. The value in the parentheses applies to the EE-SX4340.

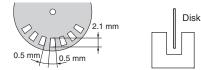
Input 0

Output

0

tPHL

- ***1.** Hysteresis denotes the difference in forward LED current value, expressed in percentage, calculated from the respective forward LED currents when the photo IC in turned from ON to OFF and when the photo IC in turned from OFF to ON.
- ***2.** The value of the response frequency is measured by rotating the disk as shown below.



Engineering Data (Reference value)

Fig 1. Forward Current vs. Collector **Dissipation Temperature Rating**

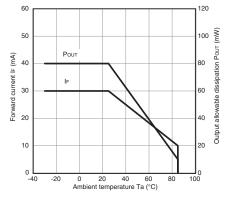


Fig 4.LED Current vs. Ambient **Temperature Characteristics (Typical)**

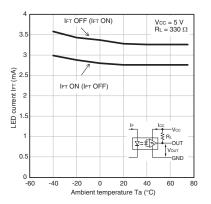


Fig 7. Current Consumption vs. Supply Fig 8. Response Delay Time vs. Voltage (Typical)

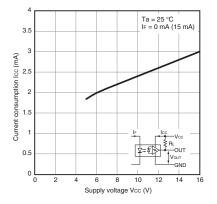


Fig 2. Forward Current vs. Forward Voltage Characteristics (Typical)

0 Input

0 Output

tPLH

EE-SX3340

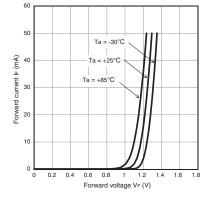
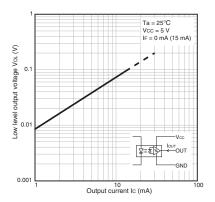


Fig 5. Low-level Output Voltage vs. **Output Current (Typical)**



Forward Current (Typical)

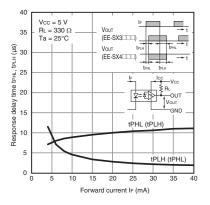


Fig 3. LED Current vs. Supply Voltage (Typical)

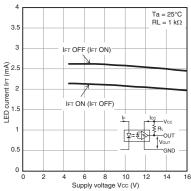


Fig 6. Low-level Output Voltage vs. **Ambient Temperature Characteristics** (Typical)

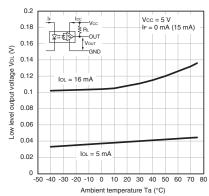
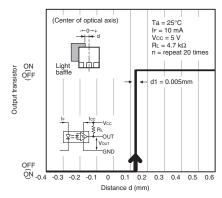


Fig 9. Repeat Sensing Position **Characteristics (Typical)**



tрны

EE-SX4340

tPLH



Safety Precautions

To ensure safe operation, be sure to read and follow the Instruction Manual provided with the Sensor.

This product is not designed or rated for ensuring safety of persons either directly or indirectly. Do not use it for such purposes.



Precautions for Safe Use

Do not use the product with a voltage or current that exceeds the rated range.

Applying a voltage or current that is higher than the rated range may result in explosion or fire.

Do not miswire such as the polarity of the power supply voltage.

Otherwise the product may be damaged or it may burn.

Do not short-circuit the load.

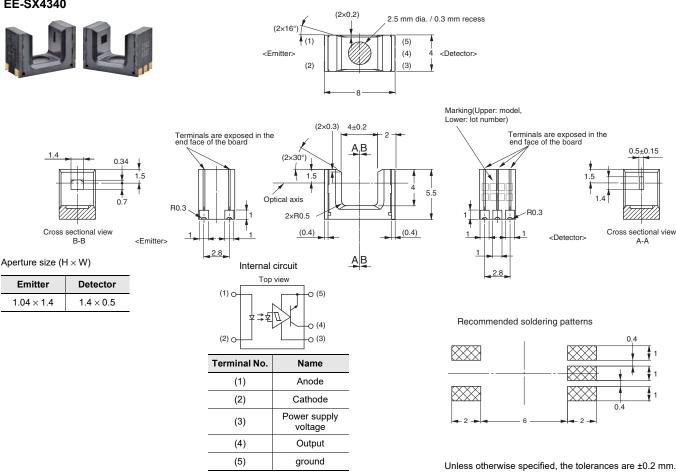
Otherwise explosion or burning may occur.

This product does not resist water. Do not use the product in places where water or oil may be sprayed onto the product.

Dimensions and Internal Circuit

Photomicrosensor

EE-SX3340 EE-SX4340



Precautions for Correct Use

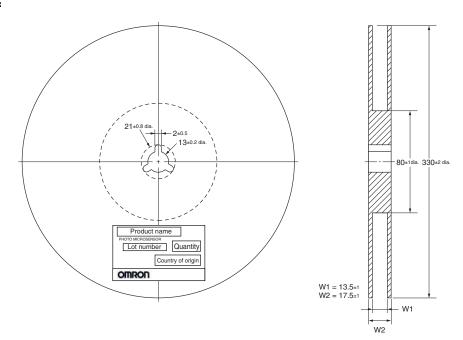
Do not use the product in atmospheres or environments that exceed product ratings. This product is for surface mounting. Refer to Soldering Information, Storage and Baking for details.

Dispose of this product as industrial waste.

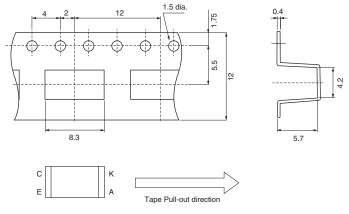
(Unit: mm)

Tape and Reel

Reel (Unit: mm) *



Tape (Unit: mm)



Note: Direction of product packing is upper figure.

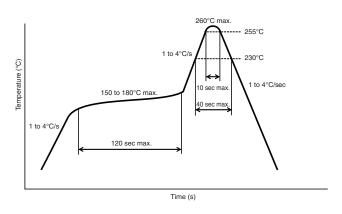
Tape quantity

1,000 pcs./reel 50 pcs./pack * * EE-SX3340-1/EE-SX4340-1 (50 pcs./pack) has no reel, only tape is attached.

Soldering Information

Reflow soldering : Temperature profile

- 1. The reflow soldering can be implemented in two times complying with the following diagram. All the temperatures in the product must be within the diagram.
- 2. The recommended thickness of the metal mask for screen printing is between 0.2 and 0.25 mm.



Storage

Storage conditions

To protect the product from the effects of humidity until the package is opened, dry-box storage is recommended. If this is not possible, store the product under the following conditions:

Temperature: 10 to 30 °C

Humidity: 60% RH max.

Baking

In case that it could not carry out the above treatment, it is able to mount by the following baking treatment. However baking treatment shall be limited only 1 time.

Recommended conditions: 60°C for 24 to 48 hours (reeled one) 100°C for 8 to 24 hours (loose one)

Manual soldering

The manual soldering should not be applied to the products, otherwise the housing may be deformed and/or the Au plating may be peeled off by heat.

Other notes

The use of infrared lamp causes the temperature at the resin to rise particularly too high.

All the temperatures in the product must be within the above diagram. Do not immerse the resin part into the solder. Even if within the above temperature diagram, there is a possibility that the gold wire in the products is broken in case that the deformation of PC board gives stress to the products.

Please confirm the conditions (including material and method of flux and cleaning) of the reflow soldering fully by actual solder reflow machine prior to the mass production use.

Treatment after open

- Reflow soldering must be done within 48 hours stored at the conditions of humidity 60% RH or less and temperature 10 to 30°C.
- If the product must be stored after it is unpacked, store it in a dry box or reseal it in a moisture-proof package with desiccant at a temperature of 10 to 30°C and a humidity of 60% RH or less. Even then, mount the product within one week.

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